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- Replaces SN74AS303
- Maximum Output Skew Between Same Phase Outputs of 1 ns
- Maximum Pulse Skew of 1 ns
- TTL-Compatible Inputs and Outputs
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- Package Options Include Plastic Small-Outline (D) Package and Standard Plastic (N) 300-mil DIPs

DORNPACKAGE (TOP VIEW)] Q2 Q3 l 16 Q4 [] 15 | Q1 GND 3 14 CLR GND 4 13 V_{CC} GND 5 IJ ∨_{CC} Q5 [] 6 11 ∐ CLK Q6 🛮 7 10 PRE Q7 9 Q8

description

The CDC303 contains eight flip-flops designed to have low skew between outputs. The eight outputs (six in-phase with CLK and two out-of-phase) toggle on successive CLK pulses. Preset (\overline{PRE}) and clear (\overline{CLR}) inputs are provided to set the Q and \overline{Q} outputs high or low independent of the clock (CLK) input.

The CDC303 has output and pulse-skew parameters $t_{sk(0)}$ and $t_{sk(p)}$ to ensure performance as a clock driver when a divide-by-two function is required.

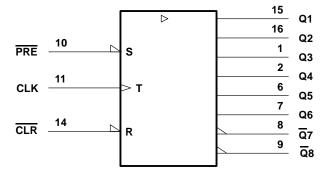
The CDC303 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

| INPUTS | | | OUTPUTS | | |
|--------|-----|------------|------------------|------------------------|--|
| CLR | PRE | CLK | Q1-Q6 | Q 7− Q 8 | |
| L | Н | Χ | L | Н | |
| Н | L | X | Н | L | |
| L | L | X | L† | L† | |
| Н | Н | \uparrow | \overline{Q}_0 | Q_0 | |
| Н | Н | L | Q ₀ | \overline{Q}_0 | |

[†] This configuration does not persist when PRE or CLR returns to its inactive (high) level.

logic symbol‡



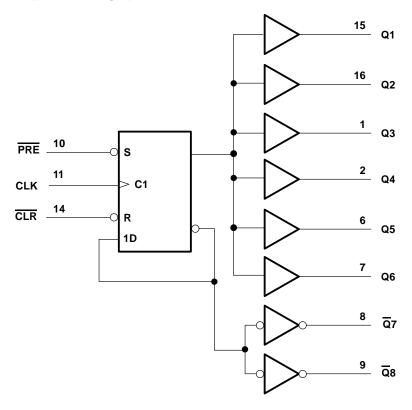
[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage, V _{CC} | 7 V |
|---|----------------|
| Input voltage, V _I | 7 V |
| Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 1): D package . | 0.77 W |
| N package . | 1.2 W |
| Storage temperature range, T _{stg} | –65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

| | | MIN | NOM | MAX | UNIT |
|--------------------|--------------------------------|-----|-----|-----|------|
| VCC | Supply voltage | 4.5 | 5 | 5.5 | V |
| VIH | High-level input voltage | 2 | | | V |
| V _{IL} | Low-level input voltage | | | 0.8 | V |
| ІОН | High-level output current | | | -24 | mA |
| loL | Low-level output current | | | 48 | mA |
| f _{clock} | Input clock frequency | | | 80 | MHz |
| TA | Operating free-air temperature | 0 | | 70 | °C |



NOTE 1: The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 300 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | MIN | TYP [†] | MAX | UNIT |
|-----------------|---|---------------------------|--------------------|------------------|------|------|
| VIK | V _{CC} = 4.5 V, | $I_{I} = -18 \text{ mA}$ | | | -1.2 | V |
| Vari | $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$ | $I_{OH} = -2 \text{ mA}$ | V _{CC} -2 | 2 | | V |
| VOH | $V_{CC} = 4.5 \text{ V},$ | $I_{OH} = -24 \text{ mA}$ | 2 | 2.8 | | V |
| V _{OL} | $V_{CC} = 4.5 \text{ V},$ | $I_{OL} = 48 \text{ mA}$ | | 0.3 | 0.5 | V |
| lį | V _{CC} = 5.5 V, | V _I = 7 V | | | 0.1 | mA |
| lН | $V_{CC} = 5.5 \text{ V},$ | V _I = 2.7 V | | | 20 | μΑ |
| I _{IL} | $V_{CC} = 5.5 \text{ V},$ | V _I = 0.4 V | | | -0.5 | mA |
| IO [‡] | V _{CC} = 5.5 V, | V _O = 2.25 V | -50 | | -150 | mA |
| Icc | V _{CC} = 5.5 V, | See Note 2 | | 40 | 70 | mA |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements over recommended ranges of supply voltage and operating free-air temperature

| | | | MIN | MAX | UNIT | |
|------------------|------------------------|---------------------|-----|-----|------|--|
| fclock | Clock frequency | | | 80 | MHz | |
| | | CLR or PRE low | 5 | | | |
| t _W P | Pulse duration | CLK high | 4 | | ns | |
| | | CLK low | 6 | | | |
| t _{su} | Setup time before CLK↑ | CLR or PRE inactive | 6 | | ns | |

switching characteristics over recommended operating free-air temperature range (see Figure 1)

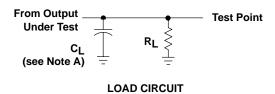
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | MIN | MAX | UNIT |
|--------------------|-----------------|---|--|-----|-----|------|
| f _{max} § | | | | 80 | | MHz |
| tplH | CLK | Q, Q | D. 500 O. C. 50 pF | 2 | 9 | ns |
| ^t PHL | OLK | Q, \overline{Q} $R_L = 500 \Omega, C_L = 50 pF$ | 2 | 9 | 115 | |
| ^t PLH | PRE or CLR | Q, Q | $R_L = 500 \Omega$, $C_L = 50 pF$ | 3 | 12 | ns |
| ^t PHL | PRE OF CLR | Q, Q | | 3 | 12 | 115 |
| | CLK | Q | | | 1 | |
| ^t sk(o) | | Q | R _L = 500 Ω, C _L = 10 pF to 30 pF, See Figure 2 | | 1 | ns |
| | | Q, Q | | | 2 | |
| t _{sk(p)} | CLK | Q, $\overline{\mathbb{Q}}$ | $R_L = 500 \Omega$, $C_L = 10 pF to 30 pF$ | | 1 | ns |
| t _r | | | | | 4.5 | ns |
| t _f | | | | | 3.5 | ns |

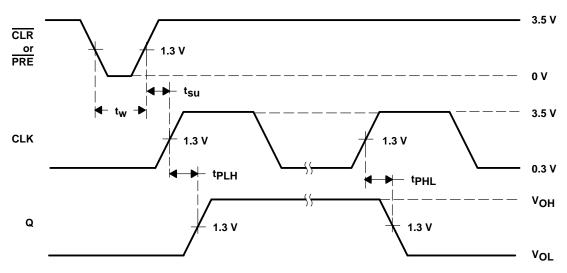
[§] f_{max} minimum values are at C_L = 0 to 30 pF.



[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS. NOTE 2: ICC is measured with CLK and PRE grounded, then with CLK and CLR grounded.

PARAMETER MEASUREMENT INFORMATION





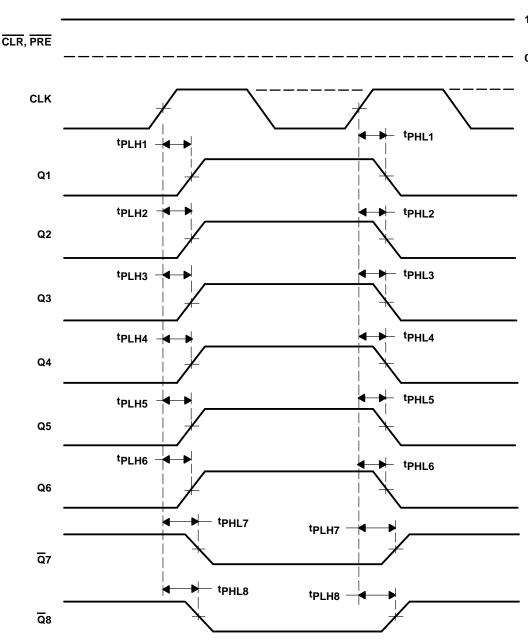
NOTES: A. C_L includes probe and jig capacitance.

B. Input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $t_r = 2.5$ ns, $t_f = 2.5$ ns.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION



NOTES: A. $t_{SK(O)}$, CLK to Q, is calculated as the greater of:

- The difference between the fastest and slowest of t_{PLHn} (n = 1, 2, 3, 4, 5, 6)
- The difference between the fastest and slowest of tpHLn (n = 1, 2, 3, 4, 5, 6)
- B. $t_{SK(0)}$, CLK to \overline{Q} , is calculated as the greater of: $|t_{PLH7} t_{PLH8}|$ and $|t_{PHL7} t_{PHL8}|$.
- C. $t_{sk(0)}$, CLK to Q and \overline{Q} , is calculated as the greater of:
 - The difference between the fastest and slowest of tp_{LHn} (n = 1, 2, 3, 4, 5, 6), tp_{HL7}, and tp_{HL8}
 - $-\,$ The difference between the fastest and slowest of t_{PHLn} (n = 1, 2, 3, 4, 5, 6), $t_{PLH7},$ and t_{PLH8}
- D. $t_{SK(p)}$ is calculated as the greater of | $t_{PLHn} t_{PHLn}$ | (n = 1, 2, 3, . . ., 8).

Figure 2. Waveforms for Calculation of $t_{sk(p)}$ and $t_{sk(p)}$



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